



Toshiba Showcases Latest Memory, Storage Solutions at Flash Memory Summit

SANTA CLARA, Calif., Aug. 11, 2015 /PRNewswire/ -- This week at the Flash Memory Summit (FMS), [Toshiba America Electronic Components, Inc.](#) (TAEC)*, a committed leader that collaborates with technology companies to create breakthrough designs, will showcase its newest memory and storage solutions. Toshiba, the inventor of NAND flash, will be on hand to further its preeminent position by debuting new solutions, displaying the latest in 3D Flash Memory and SSD technology and giving one of the Summit's keynote presentations.

All product showcases will take place from August 11-13 on the show floor at the Santa Clara Convention Center in Toshiba's theater-style booth #407. Tutorial presentations will also be given at the booth, on topics including SSD storage trends, the evolving needs of enterprises/data centers, choosing the best interfaces for specific applications and more. Shigeo (Jeff) Ohshima, technology executive, memory design and application engineering for Toshiba, will present a keynote session titled: "Advances in 3D Memory: High Density Storage for Hyperscale, Cloud Applications and Beyond." This session will take place on Tuesday, August 11, from 2:00-2:30 p.m., and will focus on the high density demands of the storage market, as well as the keys to making competitive 3D memory storage solutions a reality.

"Introducing the industry's only 48-layer solution¹ is just one example of how innovation is in Toshiba's DNA," noted Scott Nelson, senior vice president of TAEC's Memory Business Unit. "As the world's largest flash memory conference, FMS is the perfect venue for us to showcase our new offerings. These products represent more industry firsts for Toshiba, and are in step with our NAND flash leadership role."

Advances in Flash Memory

Last week, Toshiba announced the industry's first² TLC 3-bit-per-cell 256Gb³(32GB) 3D memory – the next generation of its [BiCS FLASH™](#) – and will be spotlighting this new technology in its booth. BiCS FLASH is based on Toshiba's leading-edge 48-layer stacking process. Toshiba's 3D flash memory solutions enhance the reliability of write/erase endurance, boost write speeds and are suited for a range of high density applications – including consumer electronic devices such as smartphones and laptops; as well as SSDs and enterprise applications⁴.

In addition, Toshiba has developed the world's first⁵ [16-die stacked NAND flash memory utilizing TSV technology](#) – and will be showing a prototype at FMS. This high-performance, low-power solution is targeted to enterprise SSDs.

SSDs for Client, Enterprise Applications

Toshiba will also highlight its new [12Gbit/s⁶ SAS PX04S Series](#) of enterprise SSDs with the highest random read IOPS of 270,000⁷ along with three new families of [NVMeTM⁸, PCIe[®]⁹ SSDs](#). These PCIe devices leverage low latency and power efficiency to deliver ultimate SSD performance for various applications including: high performance notebooks, thin notebooks, two-in-one/convertible notebooks and tablets, and server and storage applications. All three SSD product lines are optimized for high performance and low latency, and utilize the PCIe interface - which provides point-to-point links with the processor and reduces system bottlenecks.

The latest enterprise technology from OCZ, a Toshiba Group Company, will also make an appearance at FMS. The [Z-Drive 6000 NVMe 2.5-inch SSD series](#), which launched in May, will be demonstrated to showcase its upcoming dual-port functionality, which provides two separate data paths, offering data redundancy and eliminating single-point failures. This feature delivers high data availability for high-performance computing, enterprise resource planning, databases, transactional workloads, online analytical processing, virtual infrastructure, big data, and more.

For more information on Toshiba's flash memory solutions, please visit toshiba.com/taec/adinfo/technologymoves/ and follow the company on [Facebook](#). To learn more about Toshiba's SSDs, please visit ssd.toshiba.com.

Notes

*1: As of March 26, 2015. Toshiba survey.

*2: As of August 3, 2015. Toshiba survey.

*3: Product density is identified based on the density of memory chip(s) within the Product, not the amount of memory capacity available for data storage by the end user. Consumer-usable capacity will be less due to overhead data areas, formatting, bad blocks, and other constraints, and may also vary based on the host device and application. For details, please refer to applicable product specifications.

*4: When compared to two dimensional NAND flash memory.

*5: As of August 6, 2015. Toshiba survey.

*6: Read and write speed may vary depending on the host device, read and write conditions, and file size.

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*8: NVM Express is a trademark of NVM Express, Inc.

*9: PCIe is a registered trademark of PCI-SIG Corporation.

* BiCS FLASH is a trademark of Toshiba Corporation.

***About Toshiba Corp. and TAEC**

About TAEC

Through proven commitment, lasting relationships and advanced, reliable electronic components, Toshiba enables its customers to create market-leading designs. Toshiba is the heartbeat within product breakthroughs from OEMs, ODMs, CMs, VARs, distributors and fabless chip companies worldwide. A committed electronic components leader, Toshiba designs and manufactures high-quality flash memory-based storage solutions, solid state drives (SSDs), hard disk drives (HDDs), solid state hybrid drives (SSHDS), discrete devices, custom SoCs/ASICs, imaging products, microcontrollers, wireless components, mobile peripheral devices, advanced materials and medical tubes that make possible today's leading smartphones, tablets, cameras, medical devices, automotive electronics, industrial applications, enterprise solutions and more.

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Information in this press release, including product pricing and specifications, content of services and contact information, is current and believed to be accurate on the date of the announcement, but is subject to change without prior notice. Technical and application information contained here is subject to the most recent applicable Toshiba product specifications.

MEDIA CONTACT:

Dena Jacobson

Lages & Associates

Tel.: (949) 453-8080

dena@lages.com